



## Material Content Data Sheet



<b>Sales Product Name</b>		BTS50080-1TMC		<b>Issued</b>		29. August 2013			
<b>MA#</b>		MA001044082							
<b>Package</b>		PG-TO220-7-4		<b>Weight*</b>		1525.59 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	6.391	0.42	0.42	4189	4189	
leadframe	non noble metal	iron	7439-89-6	0.910	0.06		597		
	inorganic material	phosphorus	7723-14-0	0.273	0.02		179		
	non noble metal	copper	7440-50-8	909.052	59.58	59.66	595867	596644	
wire	non noble metal	aluminium	7429-90-5	0.911	0.06	0.06	597	597	
encapsulation	organic material	carbon black	1333-86-4	8.875	0.58		5818		
	plastics	epoxy resin	-	97.628	6.40		63994		
	inorganic material	silicondioxide	60676-86-0	485.182	31.80	38.78	318029	387841	
leadfinish	non noble metal	tin	7440-31-5	12.090	0.79	0.79	7925	7925	
plating	non noble metal	nickel	7440-02-0	0.216	0.01		141		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	1	141	
glue	plastics	Polyimide	26023-21-2	0.143	0.01	0.01	93	93	
solder	noble metal	silver	7440-22-4	0.098	0.01		64		
	non noble metal	tin	7440-31-5	0.078	0.01		51		
	non noble metal	lead	7439-92-1	3.746	0.25	0.27	2455	2570	
*deviation	< 10%					Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com